

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1577	347/54.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/09/29 15:25
L2	1577	L1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:25
L3	1152	347/56.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:26
L4	1152	L3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:26
L5	480	347/61.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:26
L6	480	L5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:26
L7	517	347/62.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:27
L8	517	L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:27

L9	868	347/70.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:28
L10	868	L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:28
L11	1401	29/610.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:28
L12	1401	L11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:28
L13	237	338/306.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:30
L14	237	L13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:30
L15	888	338/333.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:30
L16	888	L15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:30

L17	695	2 not silverbrook.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:31
L18	314	17 and @ad<="20020614"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:32
L19	350	17 and @ay<="2002"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 15:33
L20	18	(thermal thermoelastic thermo-elastic thermo adj elastic thermal adj elastic thermal-elastic) near (actuator device element) same (heater heating resistor) near (device element) same heat\$3 near conduction near (means element device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:13
L21	8343	(thermal thermoelastic thermo-elastic thermo adj elastic thermal adj elastic thermal-elastic) near (actuator device element) same (heater heating resistor) near (device element)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:19
L22	7190	21 not silverbrook.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:21
L23	3755	22 and @ad<="20020614"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:22

L24	925	23 and "347"/\$.cls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:27
L25	2	2 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:28
L26	7	4 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:29
L27	10	6 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:30
L28	13	8 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:31
L29	5	10 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:34
L30	2	12 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:34
L31	3	14 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:35

L32	3	16 and 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:36
L33	14	(heater heating resistor) near (actuator device element) same (heater heating) near (layer film material sheet) same bend near (layer film material sheet) same (heat heater heating) near conduction near (material layer film sheet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:38
L34	0	(heater heating resistor) near (actuator device element) same passive near bend near (layer film material sheet) same heat\$3 near conduct\$3 near (means device element)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:39
L35	0	(heater heating resistor) near (actuator device element) same passive near bend near (layer film material sheet) same heat\$3 near conduction near (means device element)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:40
L36	14	(heater heating resistor) near (actuator device element) same passive near bend near (layer film material sheet) same heat\$3 near conduction near (means device element material layer film sheet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:40
L37	0	(thermal thermoelastic thermo-elastic thermo adj elastic thermal adj elastic thermal-elastic) near (actuator device element) same heat\$3 near conduction near (means element device material layer film sheet) near (within in) near passive near (layer film material sheet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:42

L38	0	(thermal thermoelastic thermo-elastic thermo adj elastic thermal adj elastic thermal-elastic) near (actuator device element) same heat\$3 near conduction near (means element device material layer film sheet) same passive near (layer film sheet material)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:42
L39	0	(heater heating resistor) near (actuator device element) same (heater heating) near (layer film material sheet) same passive near (layer film material sheet) same (heat heater heating) near conduction near (material layer film sheet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/29 16:49

9/ 29/ 2009 5:45:47 PM

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